

#### SURFACE MOUNT FAST SWITCHING DIODE

### **Features**

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Breakdown Voltage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Marking Information
- Terminals: Finish NiPdAu over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2







Device Schematic

### **Ordering Information** (Note 4)

Part Number	Case	Packaging
BAS16HLP-7	X1-DFN1006-2	3,000/Tape & Reel
BAS16HLP-7B	X1-DFN1006-2	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

BAS16HLP-7

• T9

Top View Dot Denotes Cathode Side

OR T9

> Top View Bar Denotes Cathode Side

BAS16HLP-7B

Т9

Top View Bar Denotes Cathode Side

T9 = Product Type Marking Code



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		$V_{RM}$	125	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>R</sub> WM	100	V
RMS Reverse Voltage		V <sub>R(RMS)</sub>	71	V
Forward Continuous Current		I <sub>FM</sub>	215	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0ms @ t = 1.0s	I <sub>FSM</sub>	4 1 0.5	А

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_{D}$	250	mW
Thermal Resistance Junction to Ambient (Note 5)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

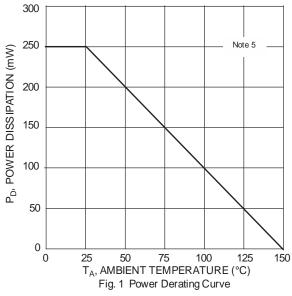
Characteristic	Symbol	Min	Max	Unit	Test Conditions		
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	100	_	V	$I_R = 100\mu A$		
		0.715		I <sub>F</sub> = 1.0mA			
Forward Voltage		_	0.855	V	$I_F = 10mA$		
Forward voltage	V <sub>F</sub>	_	1.0		$I_F = 50mA$		
		_	1.25		I <sub>F</sub> = 150mA		
	I <sub>R</sub>		500	nA	$V_R = 80V$		
Book Boyoroo Current (Note 6)		I <sub>R</sub>			50	μΑ	$V_R = 80V, T_J = +150$ °C
Peak Reverse Current (Note 6)			_	30	μA	$V_R = 25V, T_J = +150$ °C	
			30	nA	$V_R = 25V$		
Total Capacitance	Ст	_	1.5	pF	V <sub>R</sub> = 0V, f = 1.0MHz		
Reverse Recovery Time	4	t <sub>rr</sub> —	4.0	ns	$I_F = I_R = 10 \text{mA},$		
The verse hecovery fille	τrr				$I_{rr} = 0.1 \times I_R, R_L = 100\Omega$		

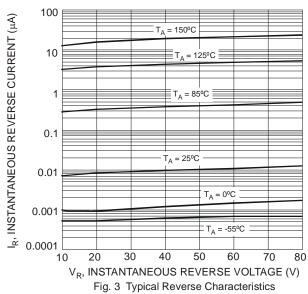
Notes:

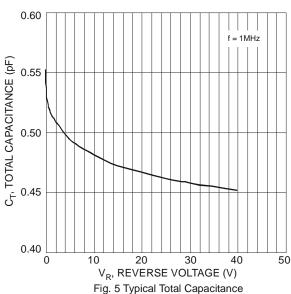
<sup>5.</sup> Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com.

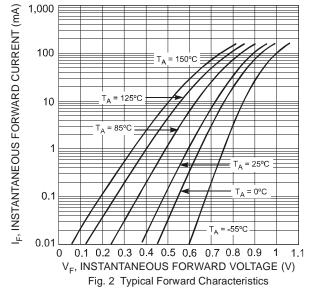
<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.











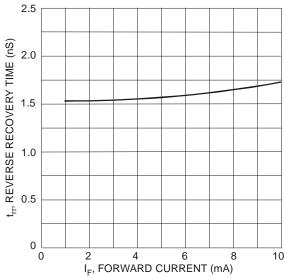
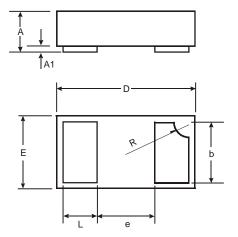


Fig. 4 Reverse Recovery Time vs. Forward Current



### **Package Outline Dimensions**

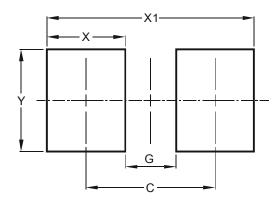
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-2					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.40		
Ĺ	0.20	0.30	0.25		
R	0.05	0.15	0.10		
All	All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G	0.30
Х	0.40
X1	1.10
Υ	0.70



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